#### Amendments to the Specification

### Please replace the paragraph beginning at page 1, line 10, with the following rewritten paragraph:

Fig. 10A is a perspective view of an ordinary direction sensor, and Fig. 10B is a sectional view of the same taken along the line A-A10B-10B. The ordinary direction sensor has:

- •bridge circuit 3 including four detecting elements 2A to 2D, placed on an upper surface of substrate 1;
  - •holder 4 holding substrate 1 and covering substrate 1 including bridge circuit 3; and
- first coil 5A and second coil 5B forming magnetic bias application parts, made of conductive wires, winding up around holder 4 with predetermined winding numbers, and being at right angles to each other.

### Please replace the paragraph beginning at page 2, line 12, with the following rewritten paragraph:

Fig. 2 is a sectional view of the direction sensor in accordance with the first exemplary embodiment of the present invention, taken along the line A -A 1B-1B of Fig. 1A.

## Please replace the paragraph beginning at page 3, line 8, with the following rewritten paragraph:

Fig. 10B is a sectional view of the ordinary direction sensor taken along the line A-A 10B-10B of Fig. 10A.

## Please replace the paragraph beginning at page 3, line 16, with the following rewritten paragraph:

Fig.1A is a perspective view of a direction sensor in accordance with a first exemplary embodiment of the present invention 1. Fig 1B is an exploded perspective view of the same.

Fig. 2 is a sectional view of the same, taken along the line A-A\_1B-1B, and Fig. 3 is a plain view of a first and a second bridge circuits, main parts of the same. Fig 4 is an electric circuit diagram of the first bridge circuit of the direction sensor in accordance with the first exemplary embodiment.

### Please replace the paragraph beginning at page 7, line 21, with the following rewritten paragraph:

First application part 16 is disposed on the upper surface of insulating layer 15A facing toward first bridge circuit 13, and second application part 17 is disposed on the upper surface of insulating layer 15B facing toward second bridge circuit 14. These parts are made of magnet such as CoPt alloy, CoCrPt alloy or ferrite of which a magnetic field is aligned into one direction. First application part 16 entirely covers first bridge circuit 13, and second application part 17 entirely covers second bridge circuit 14. Directions of the magnetic fields produced by first application parts 16 and second application part 17 are substantially 90° different as mentioned above. First and second application parts 16 and 17 generate magnetic field in a strength of 5 to 20<del>-OE</del> Oe.

## Please replace the paragraph beginning at page 8, line 3, with the following rewritten paragraph:

Next, the reason why the strength of the magnetic field is set in 5 to 20 <del>OE</del> <u>Oe</u> is explained.

# Please replace the paragraph beginning at page 10, line 26, with the following rewritten paragraph:

In this exemplary embodiment, the magnetic fields are aligned after first and second application parts 16 and 17 are formed. By doing so, the magnetic fields of first and second application parts 16 and 17 are simultaneously or successively aligned so that productivity is

improved. In placing the process, a magnet of which magnetic field has already aligned can be disposed on the upper surface of insulating layer 15 layers 15A and 15B.

# Please replace the paragraph beginning at page 11, line 20, with the following rewritten paragraph:

In second bridge circuit 14, a differential output voltage changing almost sinusoidally with an crossing angle of the terrestrial magnetism and second bridge circuit 14, is similarly detected between third output voltage electrode 20C and fourth output voltage electrode 20D.

# Please replace the paragraph beginning at page 12, line 24, with the following rewritten paragraph:

Fig. 6 is a sectional view of another direction sensor in accordance with the first exemplary embodiment of the present invention. Cover Insulating layer 15 overlays first bridge circuit 13 and second bridge circuit 14 altogether, and cover layer 21 covers first application part 16 and second application part 17 altogether.